

MOS INTEGRATED CIRCUIT

μ PD42S4260L, 424260L

3.3 V OPERATION 4 M-BIT DYNAMIC RAM

256 K-WORD BY 16-BIT, FAST PAGE MODE, BYTE READ/WRITE MODE

Description

The μ PD42S4260L, 424260L are 262 144 words by 16 bits dynamic CMOS RAMs. The fast page mode and byte read/write mode capability realize high speed access and low power consumption.

Besides, the μ PD42S4260L can execute CAS before RAS self refresh.

These are packed in 44-pin plastic TSOP (II) and 40-pin plastic SOJ.

Features

- 262 144 words by 16 bits organization
- Fast access and cycle time
- Single +3.3 V $\pm$ 0.3 V power supply

Part number	Power consumption Active (MAX.)	Access time (MAX.)	R/W cycle time (MIN.)	Fast page mode cycle time (MIN.)
μ PD42S4260L-A70, 424260L-A70	432 mW	70 ns	130 ns	45 ns
μ PD42S4260L-A80, 424260L-A80	396 mW	80 ns	150 ns	50 ns

- The μ PD42S4260L can execute $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ self refresh

Part number	Refresh cycle	Refresh	Power consumption at standby (MAX.)
μ PD42S4260L	512 cycles / 128 ms	$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ self refresh, $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh, $\overline{\text{RAS}}$ only refresh, Hidden refresh	0.36 mW (CMOS level input)
μ PD424260L	512 cycles / 8 ms	$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh, $\overline{\text{RAS}}$ only refresh, Hidden refresh	1.8 mW (CMOS level input)

- Multiplexed address inputs Row address: A0 to A8, Column address: A0 to A8

The information in this document is subject to change without notice.

Ordering Information

Part number	Access time (MAX.)	Package	Refresh
μ PD42S4260LG5-A70	70 ns	44-pin Plastic TSOP (II) (400 mil)	$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ self refresh $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh $\overline{\text{RAS}}$ only refresh Hidden refresh
μ PD42S4260LG5-A80	80 ns		
μPD42S4260LG5-A70-7KF	70 ns	44-pin Plastic TSOP (II) (400 mil) Reverse bent	
μPD42S4260LG5-A80-7KF	80 ns		
μPD42S4260LG5-A10-7KF	100 ns		
μ PD42S4260LLE-A70	70 ns	40-pin Plastic SOJ (400 mil)	
μ PD42S4260LLE-A80	80 ns		
μ PD424260LG5-A70	70 ns	44-pin Plastic TSOP (II) (400 mil)	$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh $\overline{\text{RAS}}$ only refresh Hidden refresh
μ PD424260LG5-A80	80 ns		
μPD424260LG5-A70-7KF	70 ns	44-pin Plastic TSOP (II) (400 mil) Reverse bent	
μPD424260LG5-A80-7KF	80 ns		
μPD424260LG5-A10-7KF	100 ns		
μ PD424260LLE-A70	70 ns	40-pin Plastic SOJ (400 mil)	
μ PD424260LLE-A80	80 ns		

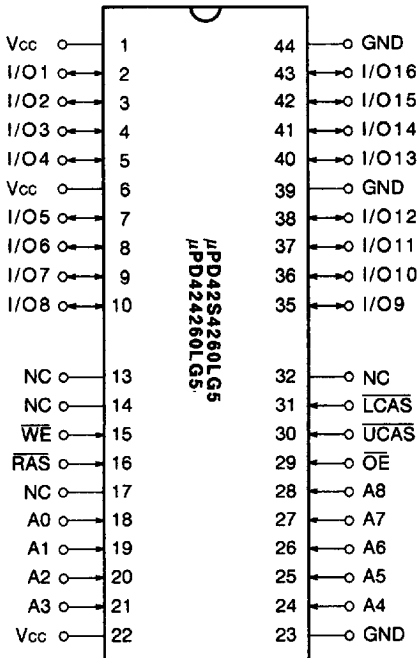
Quality Grade

Standard

Please refer to "Quality grade on NEC Semiconductor Devices" (Document number I EI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

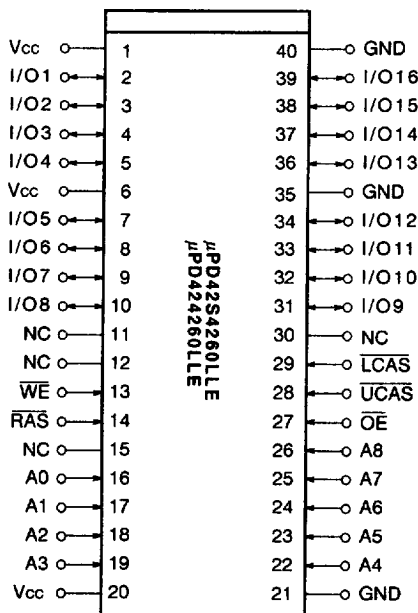
Pin Configurations (Marking Side)

44-pin Plastic TSOP(II)
(400 mil)



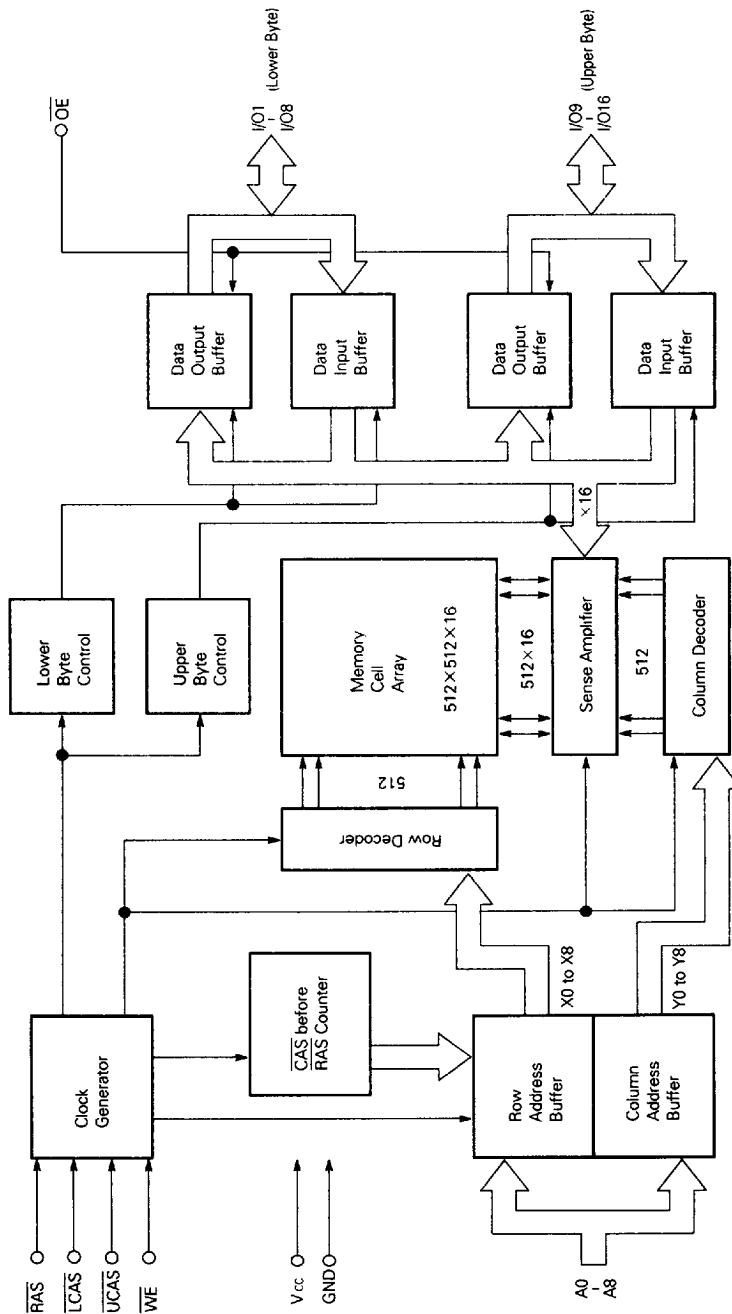
- A0 to A8 : Address Inputs
 I/O1 to I/O16 : Data Inputs/Outputs
 RAS : Row Address Strobe
 UCAS : Column Address Strobe (upper)
 LCAS : Column Address Strobe (lower)
 WE : Write Enable
 OE : Output Enable
 Vcc : Power Supply
 GND : Ground
 NC : No Connection

40-pin Plastic SOJ
(400 mil)



A0 to A8 : Address Inputs
 I/O1 to I/O16 : Data Inputs/Outputs
 RAS : Row Address Strobe
 UCAS : Column Address Strobe (upper)
 LCAS : Column Address Strobe (lower)
 WE : Write Enable
 OE : Output Enable
 Vcc : Power Supply
 GND : Ground
 NC : No Connection

Block Diagram



Input/Output Pin Functions

The μPD42S4260L, 424260L have input pins $\overline{\text{RAS}}$, $\overline{\text{CAS}}$ ^{Note}, $\overline{\text{WE}}$, $\overline{\text{OE}}$, A0 to A8 and input/output pins I/O1 to I/O16.

Pin name	Input/Output	Function
$\overline{\text{RAS}}$ (Row address strobe)	Input	$\overline{\text{RAS}}$ activates the sense amplifier by latching a row address (A0 to A8) and selecting a corresponding word line. It refreshes memory cell array of one line selected by the row address (A0 to A8). It also selects the following function. • $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh
$\overline{\text{CAS}}$ (Column address strobe)	Input	$\overline{\text{CAS}}$ activates data input/output circuit by latching column address (A0 to A8) and selecting a digit line connected with the sense amplifier.
A0 to A8 (Address inputs)	Input	9-bit address bus. Input total 18-bit of address signal, upper 9-bit and lower 9-bit in sequence (address multiplex method). Therefore, one word (16-bit) is selected from 262 144-word by 16-bit memory cell array. In actual operation, latch row address by specifying row address and activating $\overline{\text{RAS}}$. Then, switch the address bus to column address and activate $\overline{\text{CAS}}$. Each address is taken into the device when $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ are activated. Therefore, the address input setup time (t_{ASR} , t_{ASC}) and hold time (t_{RAH} , t_{CAH}) are specified for the activation of $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$.
$\overline{\text{WE}}$ (Write enable)	Input	Write control signal. Write operation is executed by activating $\overline{\text{RAS}}$, $\overline{\text{CAS}}$ and $\overline{\text{WE}}$.
$\overline{\text{OE}}$ (Output enable)	Input	Read control signal. Read operation can be executed by activating $\overline{\text{RAS}}$, $\overline{\text{CAS}}$ and $\overline{\text{OE}}$. If $\overline{\text{WE}}$ is activated during read operation, $\overline{\text{OE}}$ is to be ineffective in the device. Therefore, read operation cannot be executed.
I/O1 to I/O16 (Data inputs/outputs)	Input/Output	16-bit data bus. I/O1 to I/O16 are used to input/output data.

Note $\overline{\text{CAS}}$ means $\overline{\text{UCAS}}$ and $\overline{\text{LCAS}}$.

Electrical Specifications

- CAS means UCAS and LCAS.
- All voltages are referenced to GND.
- After power up, wait more than 100 μs and then, execute eight CAS before RAS or RAS only refresh cycles as dummy cycles to initialize internal circuit.

Absolute Maximum Ratings

Parameter	Symbol	Condition	Rating	Unit
Voltage on Any Pin Relative to GND	V _T		-0.5 to +4.6	V
Supply Voltage	V _{CC}		-0.5 to +4.6	V
Output Current	I _O		20	mA
Power Dissipation	P _D		1	W
Operating Temperature	T _{opt}		0 to +70	°C
Storage Temperature	T _{stg}		-55 to +125	°C

Caution Exposing the device to stress above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Condition	MIN	TYP.	MAX.	Unit
Supply Voltage	V _{CC}		3.0	3.3	3.6	V
High Level Input Voltage	V _{IH}		2.0		V _{CC} +0.3	V
Low Level Input Voltage	V _{IL}		-0.3		+0.8	V
Ambient Temperature	T _a		0		70	°C

Capacitance (T_a = 25 °C , f = 1 MHz)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Input Capacitance	C _{I1}	Address			5	pF
	C _{I2}	RAS, CAS, WE, OE			7	pF
Data Input/Output Capacitance	C _{I/O}	I/O			7	pF

DC Characteristics (Recommended Operating Conditions unless otherwise noted)

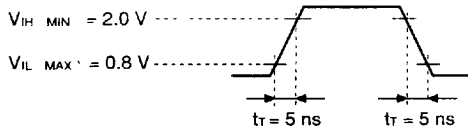
Parameter	Symbol	Test Condition	MIN.	TYP.	MAX.	Unit	Notes
Operating current	I _{CC1}	RAS, CAS Cycling			120	mA	1, 2, 3
		trc = trc (MIN.)			110		
		I _O = 0 mA					
Standby current	μPD42S4260L μPD424260L	I _{CC2}	RAS, CAS ≥ V _{IH} (MIN.), I _O = 0 mA		0.5	mA	
			RAS, CAS ≥ V _{CC} - 0.2 V, I _O = 0 mA		0.1		
			RAS, CAS ≥ V _{IH} (MIN.), I _O = 0 mA		2		
			RAS, CAS ≥ V _{CC} - 0.2 V, I _O = 0 mA		0.5		
RAS only refresh current	I _{CC3}	RAS Cycling, CAS ≥ V _{IH} (MIN.)	trac = 70 ns		120	mA	1, 2, 3, 4
			trac = 80 ns		110		
			trc = trc (MIN.), I _O = 0 mA				
Operating current (Fast page mode)	I _{CC4}	RAS ≤ V _{IL} (MAX.), CAS Cycling	trac = 70 ns		80	mA	1, 2, 5
			trac = 80 ns		70		
			tpc = tpc (MIN.), I _O = 0 mA				
CAS before RAS refresh current	I _{CC5}	RAS Cycling	trac = 70 ns		120	mA	1, 2
			trc = trc (MIN.)		110		
			I _O = 0 mA				
CAS before RAS long refresh current (512 Cycles / 128 ms, only for the μPD42S4260L)	I _{CC6}	CAS before RAS refresh : 512 Cycles / 128 ms RAS, CAS : V _{CC} -0.2 V ≤ V _{IH} ≤ V _{IH} (MAX.) 0 V ≤ V _{IL} ≤ 0.2 V	trac ≤ 200 ns		100	μA	1, 2
			Standby : RAS, CAS ≥ V _{CC} -0.2 V Address : V _{IH} or V _{IL} WE, OE : V _{IH} I _O = 0 mA	trac ≤ 1 μs	150		
Self refresh current (CAS before RAS self refresh, only for the μPD42S4260L)	I _{CC7}	RAS, CAS : V _{CC} -0.2 V ≤ V _{IH} ≤ V _{IH} (MAX.) 0 V ≤ V _{IL} ≤ 0.2 V I _O = 0 mA			100	μA	2
Input leakage current	I _I (L)	V _I = 0 to 3.6 V All other pins not under test = 0 V	-5		+5	μA	
Output leakage current	I _O (L)	V _O = 0 to 3.6 V Output is disabled (Hi-Z)	-5		+5	μA	
High level output voltage	V _{OH}	I _O = -2.0 mA	2.4			V	
Low level output voltage	V _{OL}	I _O = +2.0 mA			0.4	V	

- Notes**
1. I_{CC1}, I_{CC3}, I_{CC4}, I_{CC5} and I_{CC6} depend on cycle rates (trc and tpc).
 2. Specified values are obtained with outputs unloaded.
 3. I_{CC1} and I_{CC3} are measured assuming that address can be changed once or less during RAS ≤ V_{IL} (MAX.) and CAS ≥ V_{IH} (MIN.).
 4. I_{CC3} is measured assuming that all column address inputs are held at either high or low.
 5. I_{CC4} is measured assuming that all column address inputs are switched only once during each fast page cycle.

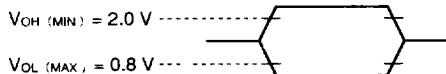
AC Characteristics (Recommended Operating Conditions unless otherwise noted)

AC Characteristics Test Conditions

(1) Input timing specification



(2) Output timing specification



(3) Loading conditions are 100 pF + 1 TTL.

Common to Read, Write, Read Modify Write Cycle

Parameter		Symbol	t _{RAC} = 70 ns		t _{RAC} = 80 ns		Unit	Notes
			MIN.	MAX.	MIN.	MAX.		
Read / Write Cycle Time		t _{RC}	130	–	150	–	ns	
RAS Precharge Time		t _{RP}	50	–	60	–	ns	
CAS Precharge Time		t _{CPN}	10	–	10	–	ns	
RAS Pulse Width		t _{RAS}	70	10 000	80	10 000	ns	
CAS Pulse Width		t _{CAS}	20	10 000	20	10 000	ns	
RAS Hold Time		t _{RSH}	20	–	20	–	ns	
CAS Hold Time		t _{CSH}	70	–	80	–	ns	
RAS to CAS Delay Time		t _{RCD}	20	50	20	60	ns	1
RAS to Column Address Delay Time		t _{RAD}	15	35	15	40	ns	1
CAS to RAS Precharge Time		t _{CRP}	10	–	10	–	ns	2
Row Address Setup Time		t _{ASR}	0	–	0	–	ns	
Row Address Hold Time		t _{RAH}	0	–	10	–	ns	
Column Address Setup Time		t _{ASC}	0	–	0	–	ns	
Column Address Hold Time		t _{CAH}	15	–	15	–	ns	
OE Lead Time Referenced to RAS		t _{OES}	0	–	0	–	ns	
CAS to Data Setup Time		t _{CLZ}	0	–	0	–	ns	
OE to Data Setup Time		t _{OLZ}	0	–	0	–	ns	
OE to Data Delay Time		t _{OED}	15	–	15	–	ns	
Masked Byte Write Hold Time Referenced to RAS		t _{MRH}	0	–	0	–	ns	
Transition Time (Rise and Fall)		t _T	3	50	3	50	ns	
Refresh Time	μPD42S4260L	t _{REF}	–	128	–	128	ms	3
	μPD424260L		–	8	–	8	ms	

Notes 1. For read cycles, access time is defined as follows:

Input Conditions	Access Time	Access Time from $\overline{\text{RAS}}$
$\text{trAD} \leq \text{trAD}(\text{MAX})$ and $\text{trCD} \leq \text{trCD}(\text{MAX})$	$\text{trAC}(\text{MAX})$	$\text{trAC}(\text{MAX})$
$\text{trAD} > \text{trAD}(\text{MAX})$ and $\text{trCD} \leq \text{trCD}(\text{MAX})$	$\text{tAA}(\text{MAX})$	$\text{trAD} + \text{tAA}(\text{MAX})$
$\text{trCD} > \text{trCD}(\text{MAX})$	$\text{tCAC}(\text{MAX})$	$\text{trCD} + \text{tCAC}(\text{MAX})$

$\text{trAD}(\text{MAX})$ and $\text{trCD}(\text{MAX})$ are specified as reference points only ; they are not restrictive operating parameters. They are used to determine which access time(trAC , tAA or tCAC) is to be used for finding out when output data will be available. Therefore, the input conditions $\text{trAD} \geq \text{trAD}(\text{MAX})$ and $\text{trCD} \geq \text{trCD}(\text{MAX})$ will not cause any operation problems.

- $\text{tCRP}(\text{MIN})$ requirement is applied for RAS, CAS cycles preceded by any cycle.
- This specification is applied only for the μPD42S4260L.

Read Cycle

Parameter	Symbol	$\text{trAC} = 70 \text{ ns}$		$\text{trAC} = 80 \text{ ns}$		Unit	Notes
		MIN	MAX.	MIN.	MAX.		
Access Time from $\overline{\text{RAS}}$	trAC	–	70	–	80	ns	1
Access Time from CAS	tCAC	–	20	–	20	ns	1
Access Time from Column Address	tAA	–	35	–	40	ns	1
Access Time from $\overline{\text{OE}}$	tOEA	–	20	–	20	ns	
Column Address Lead Time Referenced to $\overline{\text{RAS}}$	trAL	35	–	40	–	ns	
Read Command Setup Time	trCS	0	–	0	–	ns	
Read Command Hold Time Referenced to $\overline{\text{RAS}}$	trRH	0	–	0	–	ns	2
Read Command Hold Time Referenced to $\overline{\text{CAS}}$	trCH	0	–	0	–	ns	2
Output Buffer Turn-off Delay Time from $\overline{\text{OE}}$	tOEZ	0	15	0	15	ns	3
Output Buffer Turn-off Delay Time from CAS	tOFF	0	15	0	15	ns	3

Notes 1. For read cycles, access time is defined as follows:

Input Conditions	Access Time	Access Time from $\overline{\text{RAS}}$
$\text{trAD} \leq \text{trAD}(\text{MAX})$ and $\text{trCD} \leq \text{trCD}(\text{MAX})$	$\text{trAC}(\text{MAX})$	$\text{trAC}(\text{MAX})$
$\text{trAD} > \text{trAD}(\text{MAX})$ and $\text{trCD} \leq \text{trCD}(\text{MAX})$	$\text{tAA}(\text{MAX})$	$\text{trAD} + \text{tAA}(\text{MAX})$
$\text{trCD} > \text{trCD}(\text{MAX})$	$\text{tCAC}(\text{MAX})$	$\text{trCD} + \text{tCAC}(\text{MAX})$

$\text{trAD}(\text{MAX})$ and $\text{trCD}(\text{MAX})$ are specified as reference points only ; they are not restrictive operating parameters. They are used to determine which access time(trAC , tAA or tCAC) is to be used for finding out when output data will be available. Therefore, the input conditions $\text{trAD} \geq \text{trAD}(\text{MAX})$ and $\text{trCD} \geq \text{trCD}(\text{MAX})$ will not cause any operation problems.

- Either $\text{trCH}(\text{MIN})$ or $\text{trRH}(\text{MIN})$ should be met in read cycles.
- $\text{tOFF}(\text{MAX})$ and $\text{tOEZ}(\text{MAX})$ define the time when the output achieves the condition of Hi-Z and is not referenced to V_{OH} or V_{OL} .

Write Cycle

Parameter	Symbol	t _{RAC} = 70 ns		t _{RAC} = 80 ns		Unit	Notes
		MIN.	MAX.	MIN.	MAX.		
$\overline{\text{WE}}$ Hold Time Referenced to $\overline{\text{CAS}}$	t _{WCH}	10	–	15	–	ns	1
$\overline{\text{WE}}$ Pulse Width	t _{WP}	10	–	15	–	ns	1
$\overline{\text{WE}}$ Lead Time Referenced to $\overline{\text{RAS}}$	t _{RWL}	20	–	20	–	ns	
$\overline{\text{WE}}$ Lead Time Referenced to $\overline{\text{CAS}}$	t _{CWL}	15	–	15	–	ns	
$\overline{\text{WE}}$ Setup Time	t _{WCS}	0	–	0	–	ns	2
OE Hold Time	t _{OEH}	0	–	0	–	ns	
Data-in Setup Time	t _{DS}	0	–	0	–	ns	3
Data-in Hold Time	t _{DH}	15	–	15	–	ns	3

- Notes**
1. t_{WPI(MIN.)} is applied for late write cycles or read modify write cycles. In early write cycles, t_{WCH(MIN.)} should be met.
 2. If t_{WCS} ≥ t_{WCS(MIN.)}, the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle.
 3. t_{DS(MIN.)} and t_{DH(MIN.)} are referenced to the $\overline{\text{CAS}}$ falling edge in early write cycles. In late write cycles and read modify write cycles, they are referenced to the $\overline{\text{WE}}$ falling edge.

Read Modify Write Cycle

Parameter	Symbol	t _{RAC} = 70 ns		t _{RAC} = 80 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.		
Read Modify Write Cycle Time	t _{RWC}	175	–	200	–	ns	
RAS to $\overline{\text{WE}}$ Delay Time	t _{RWD}	90	–	105	–	ns	1
CAS to $\overline{\text{WE}}$ Delay Time	t _{CWD}	40	–	45	–	ns	1
Column Address to $\overline{\text{WE}}$ Delay Time	t _{AWD}	55	–	65	–	ns	1

- Note**
1. If t_{WCS} ≥ t_{WCS(MIN.)}, the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle. If t_{RWD} ≥ t_{RWD(MIN.)}, t_{CWD} ≥ t_{CWD(MIN.)}, t_{AWD} ≥ t_{AWD(MIN.)}, and t_{CPWD} ≥ t_{CPWD(MIN.)}, the cycle is a read modify write cycle and the data out will contain data read from the selected cell. If neither of the above conditions is met, the state of the data out is indeterminate.

Fast Page Mode

Parameter	Symbol	t _{RAC} = 70 ns		t _{RAC} = 80 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.		
Fast Page Mode Cycle Time	t _{PC}	45	–	50	–	ns	
Access Time from $\overline{\text{CAS}}$ Precharge	t _{ACP}	–	40	–	45	ns	
RAS Pulse Width	t _{RASP}	70	125 000	80	125 000	ns	
$\overline{\text{CAS}}$ Precharge Time	t _{CP}	10	–	10	–	ns	
RAS Hold Time from $\overline{\text{CAS}}$ Precharge	t _{RHCP}	40	–	45	–	ns	
Read Modify Write Cycle Time	t _{PRWC}	90	–	100	–	ns	
$\overline{\text{CAS}}$ Precharge to $\overline{\text{WE}}$ Delay Time	t _{CPWD}	60	–	70	–	ns	1

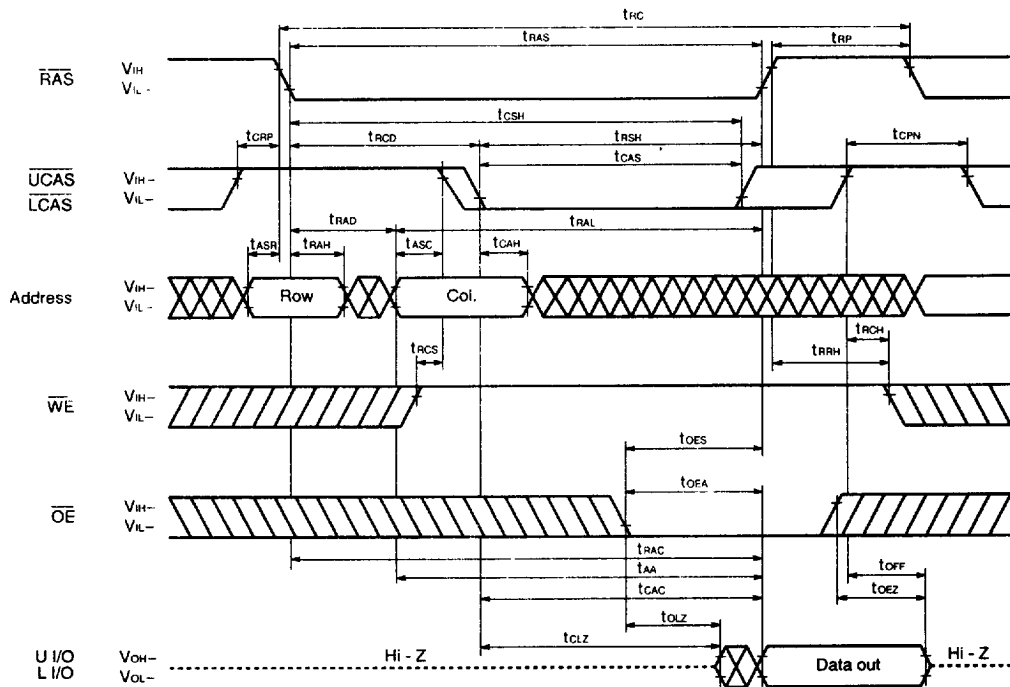
Note 1. If $\text{twcs} \geq \text{twcs}(\text{MIN.})$, the cycle is an early write cycle and the data out will remain Hi - Z through the entire cycle. If $\text{trwd} \geq \text{trwd}(\text{MIN.})$, $\text{tcwd} \geq \text{tcwd}(\text{MIN.})$, $\text{tawd} \geq \text{tawd}(\text{MIN.})$, and $\text{tcpwd} \geq \text{tcpwd}(\text{MIN.})$, the cycle is a read modify write cycle and the data out will contain data read from the selected cell. If neither of the above conditions is met, the state of the data out is indeterminate.

Refresh Cycle

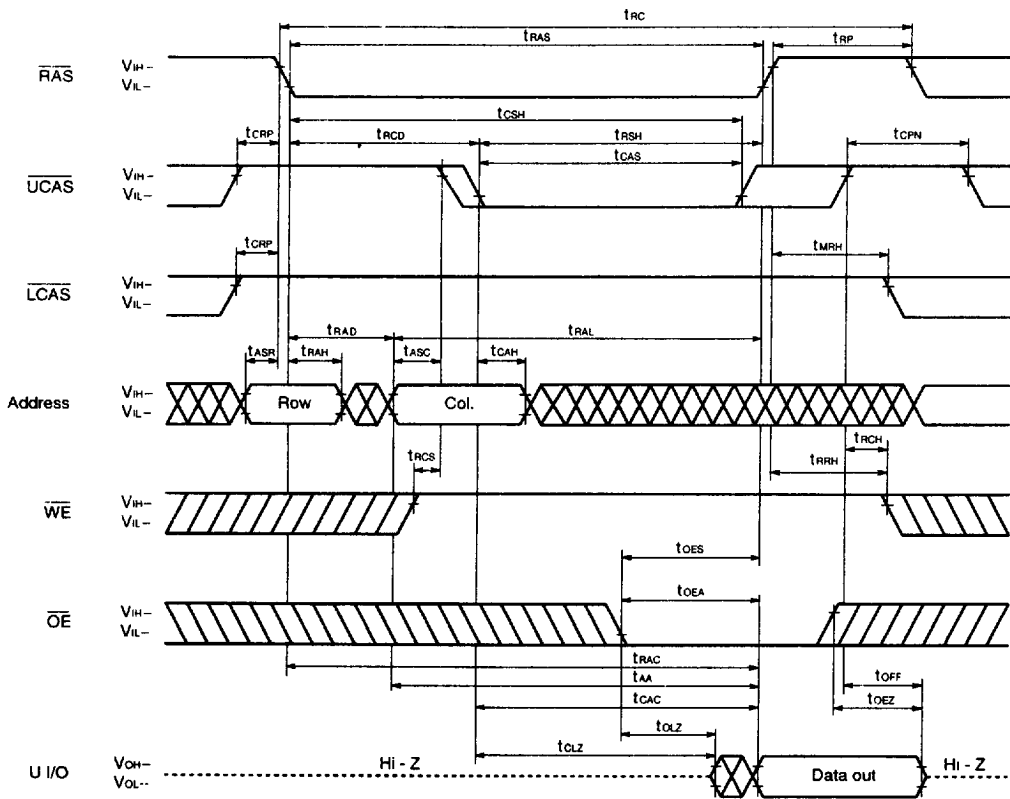
Parameter	Symbol	t _{RAC} = 70 ns		t _{RAC} = 80 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.		
$\overline{\text{CAS}}$ Setup Time	t _{CSR}	5	–	5	–	ns	
$\overline{\text{CAS}}$ Hold Time ($\overline{\text{CAS}}$ before RAS Refresh)	t _{CHR}	10	–	10	–	ns	
RAS Precharge $\overline{\text{CAS}}$ Hold Time	t _{RPC}	10	–	10	–	ns	
RAS Pulse Width ($\overline{\text{CAS}}$ before RAS Self Refresh Cycle)	t _{RASS}	100	–	100	–	μs	1
RAS Precharge Time ($\overline{\text{CAS}}$ before RAS Self Refresh Cycle)	t _{RPS}	130	–	150	–	ns	1
$\overline{\text{CAS}}$ Hold Time ($\overline{\text{CAS}}$ before RAS Self Refresh Cycle)	t _{CHS}	–50	–	–50	–	ns	1
$\overline{\text{WE}}$ Hold Time (Hidden Refresh Cycle)	t _{WHR}	15	–	15	–	ns	

Note 1. This specification is applied only for the μPD42S4260L.

Read Cycle

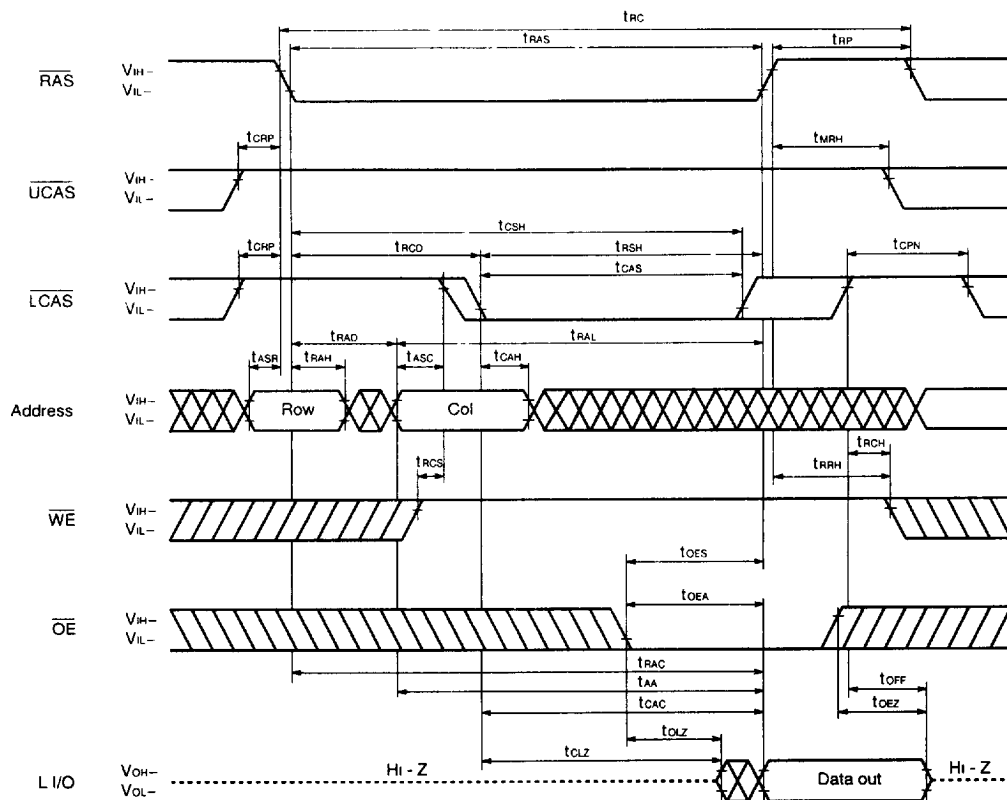


Upper Byte Read Cycle



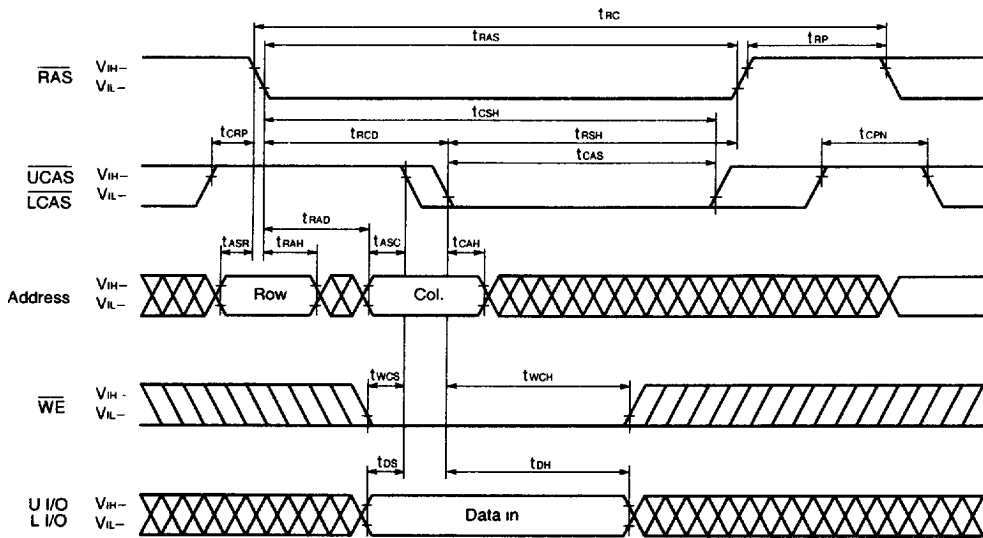
Remark L I/O : Hi-Z

Lower Byte Read Cycle



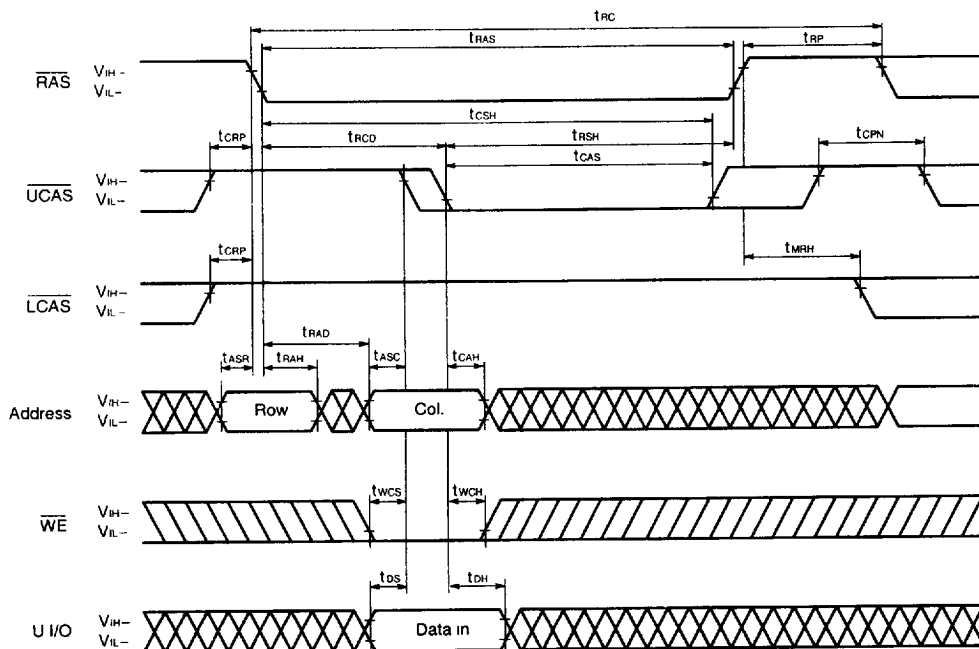
Remark U I/O : Hi-Z

Early Write Cycle



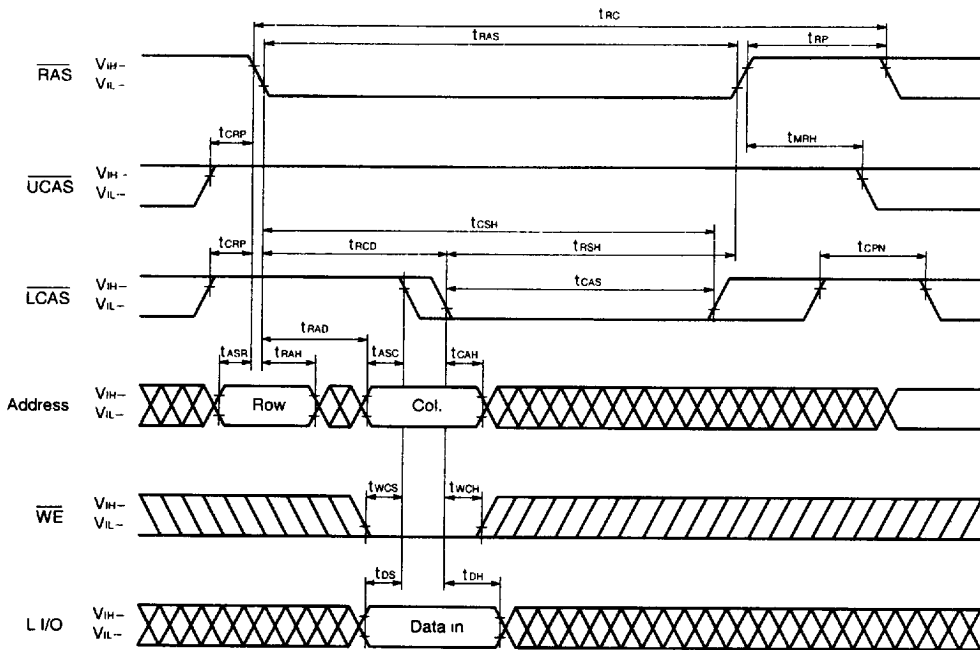
Remark $\overline{\text{OE}}$: Don't care

Upper Byte Early Write Cycle



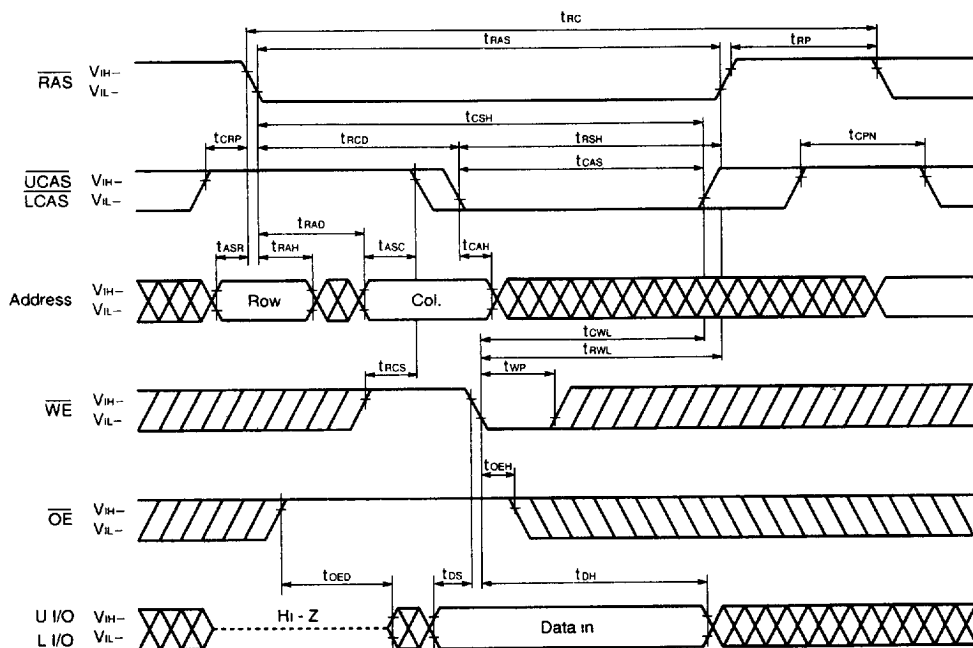
Remark $\overline{OE}$, L I/O : Don't care

Lower Byte Early Write Cycle

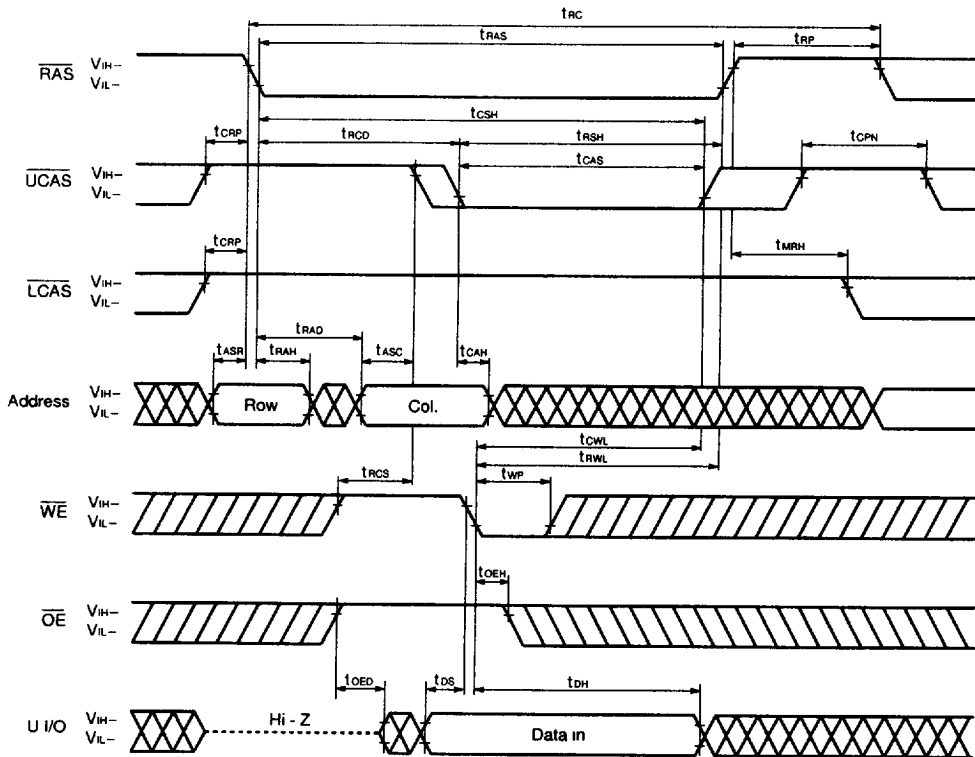


Remark $\overline{OE}$, $\overline{U}$ I/O : Don't care

Late Write Cycle

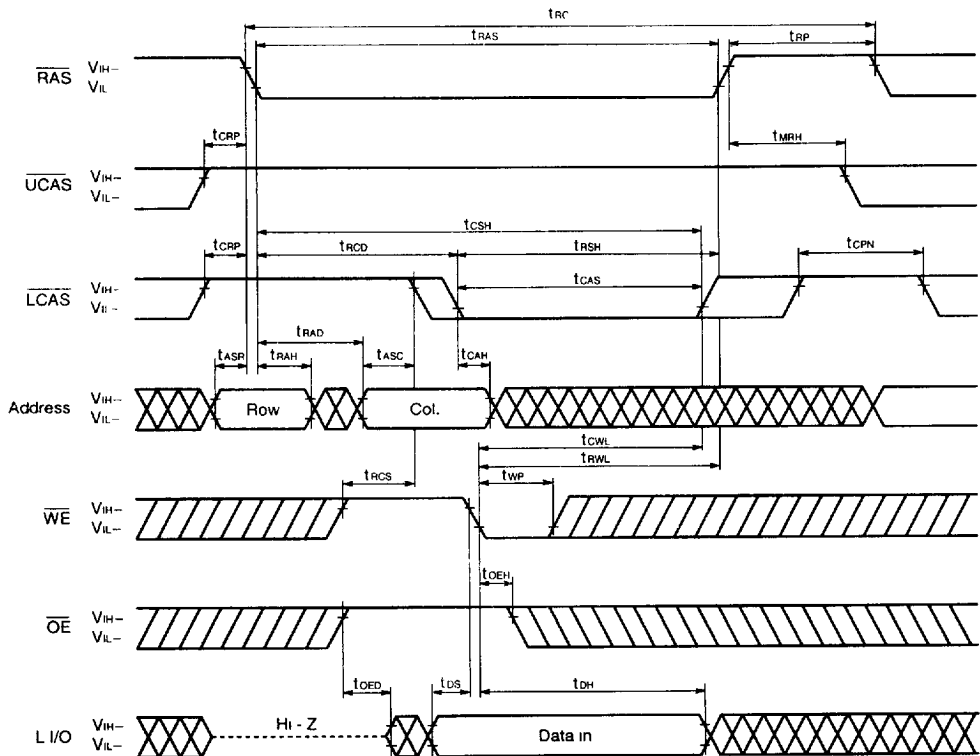


Upper Byte Late Write Cycle



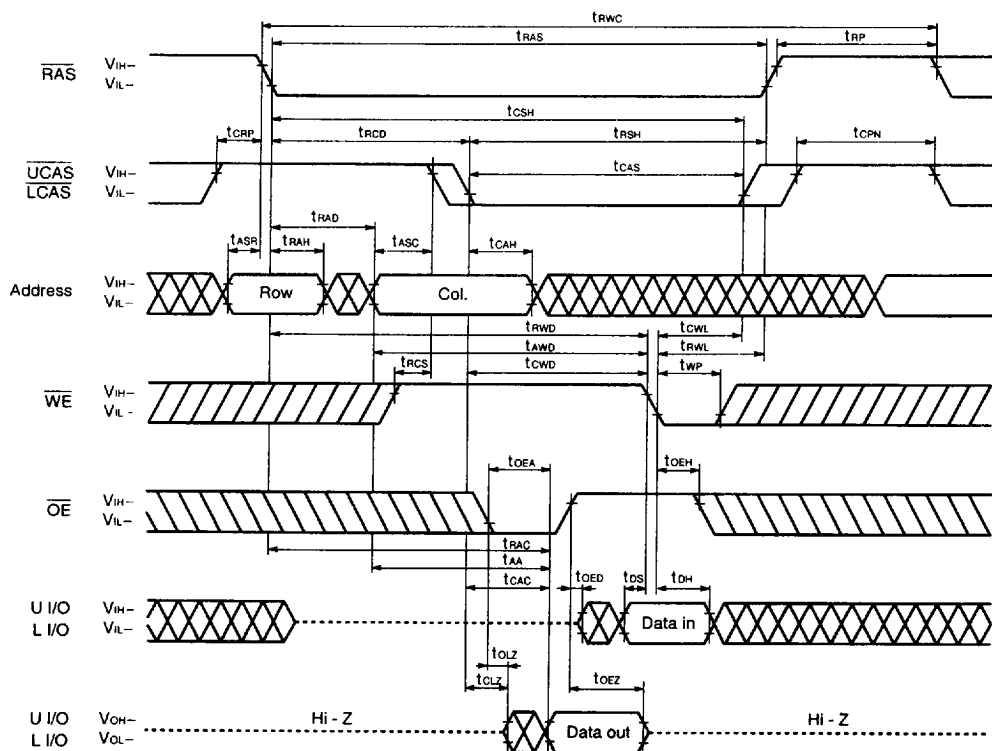
Remark L I/O : Don't care

Lower Byte Late Write Cycle



Remark U I/O : Don't care

Read Modify Write Cycle

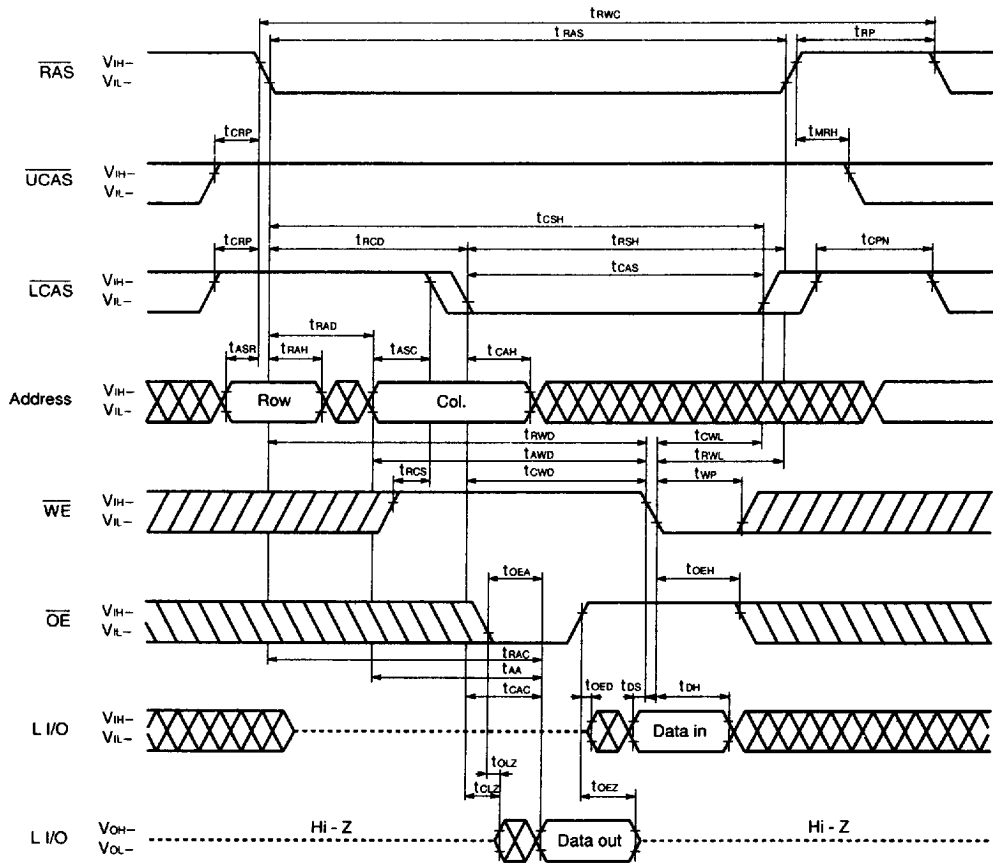


The timing diagram illustrates the relationship between the 64K1602 LCD controller and the 64K1601 LCD module. The signals and their timing parameters are as follows:

- RAS**: Row Address Strobe. Timing parameters: t_{RAS} (high pulse), t_{RWC} (high-to-low transition), t_{RP} (low-to-high transition), t_{CRP} (low-to-high transition).
- UCAS**: User Command Address Strobe. Timing parameters: t_{CRP} (low-to-high transition), t_{RCD} (low-to-high transition), t_{CSH} (high-to-low transition), t_{RSH} (high-to-low transition), t_{CAS} (low-to-high transition), t_{CPN} (low-to-high transition).
- LCAS**: LCD Command Address Strobe. Timing parameters: t_{CRP} (low-to-high transition), t_{MRH} (high-to-low transition).
- Address**: Data bus for Row and Column addresses. Timing parameters: t_{ASR} (low-to-high transition), t_{RAH} (high-to-low transition), t_{ASC} (low-to-high transition), t_{CAH} (high-to-low transition).
- WE**: Write Enable. Timing parameters: t_{RCS} (low-to-high transition), t_{RWD} (high-to-low transition), t_{AWD} (high-to-low transition), t_{CWD} (high-to-low transition), t_{WPL} (low-to-high transition).
- OE**: Output Enable. Timing parameters: t_{OEa} (low-to-high transition), t_{OEh} (high-to-low transition), t_{RAC} (low-to-high transition), t_{AA} (high-to-low transition), t_{CAC} (low-to-high transition).
- U I/O**: User I/O. Timing parameters: t_{OLZ} (low-to-high transition), t_{CLZ} (high-to-low transition), t_{OEZ} (low-to-high transition), t_{ds} (data setup time), t_{OH} (data hold time).

779

Lower Byte Read Modify Write Cycle



Remark In this cycle, the input data to Upper I/O is ineffective. The data out of that remains Hi-Z.

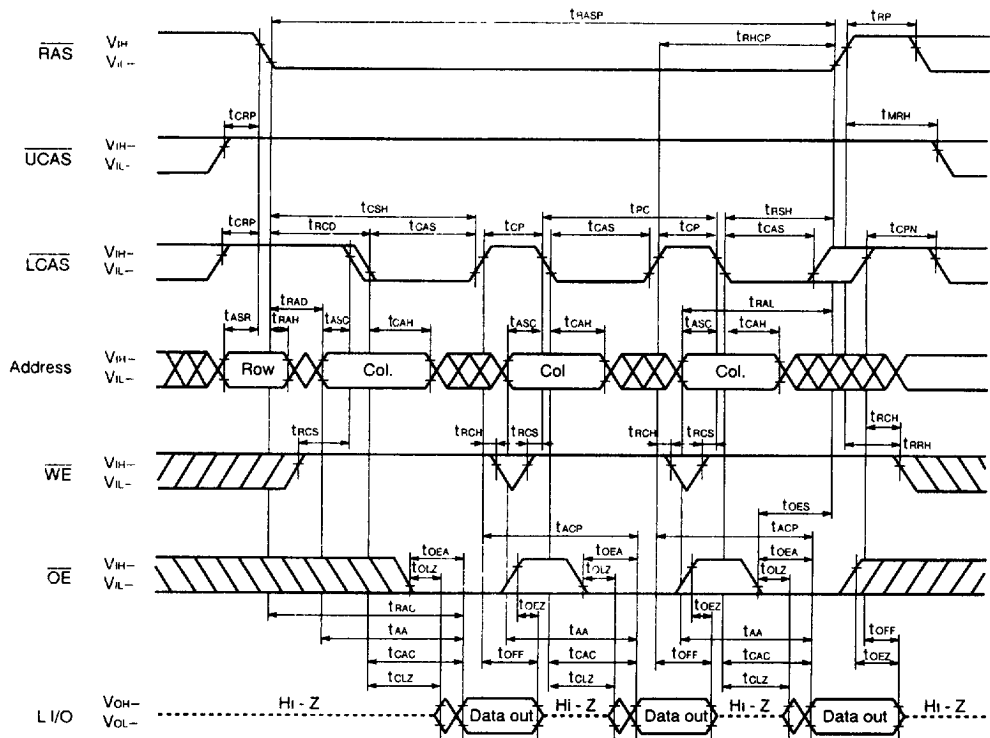
[illegible]

781

[illegible]

In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{\text{CAS}}$ cycles within the same $\overline{\text{RAS}}$ cycle.

Fast Page Mode Lower Byte Read Cycle

**Remark** U I/O : Hi-Z

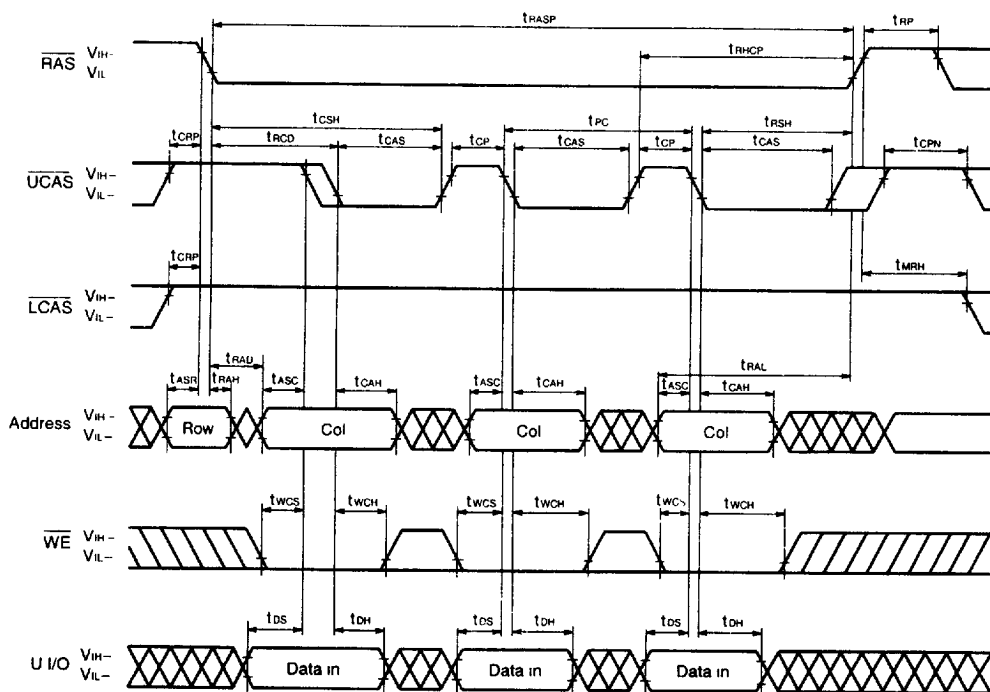
In the fast page mode, read, write and read modify write cycles are available for each of the consecutive CAS cycles within the same RAS cycle.

The diagram illustrates the timing relationships for a 64Kx16 DRAM. The signals and their timing parameters are as follows:

- RAS:** V_{IH} and V_{IL} levels. Timing parameters: t_{RASP} (RAS pulse width), t_{RHCP} (RAS hold time), t_{RP} (RAS precharge time).
- UCAS/LCAS:** V_{IH} and V_{IL} levels. Timing parameters: t_{CRP} (UCAS/LCAS precharge time), t_{CSH} (UCAS/LCAS setup time), t_{CCO} (UCAS/LCAS clock-to-output delay), t_{CAS} (UCAS/LCAS access time), t_{CP} (UCAS/LCAS clock-to-precharge delay), t_{CRSH} (UCAS/LCAS refresh time), t_{CPN} (UCAS/LCAS precharge to next cycle time).
- Address:** V_{IH} and V_{IL} levels. Timing parameters: t_{ASR} (Address setup time), t_{RAH} (Address hold time), t_{ASC} (Address-to-column access time), t_{CAH} (Column access hold time), t_{AL} (Address-to-row access time).
- WE:** V_{IH} and V_{IL} levels. Timing parameters: t_{WCS} (Write enable setup time), t_{WCH} (Write enable hold time).
- U/I/O L I/O:** V_{IH} and V_{IL} levels. Timing parameters: t_{DS} (Data setup time), t_{DH} (Data hold time).

In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{\text{CAS}}$ cycles within the same $\overline{\text{RAS}}$ cycle.

Fast Page Mode Upper Byte Early Write Cycle



Remark $\overline{OE}$, L I/O : Don't care

In the fast page mode, read, write and read modify write cycles are available for each of the consecutive CAS cycles within the same RAS cycle.

The timing diagram illustrates the relationship between several control and data signals and their respective timing parameters:

- RAS:** Row Address Strobe. Parameters include t_{RASP} (pulse width), t_{RHCP} (hold time after pulse), t_{RP} (return time to high), and t_{CRP} (setup time before pulse).
- UCAS:** Upper Chip Address Strobe. Parameters include t_{MRH} (hold time after pulse).
- LCAS:** Lower Chip Address Strobe. Parameters include t_{CRP} (setup time before pulse), t_{CSH} (hold time after pulse), t_{CP} (pulse width), t_{CAS} (access time), t_{RSH} (hold time after pulse), and t_{CPN} (non-pulse width).
- Address:** Shows Row and Column address periods. Parameters include t_{ASR} (setup time), t_{RAH} (hold time), t_{ASC} (access time), t_{CAH} (column access time), t_{RAD} (row address delay), t_{RAL} (row address latency), and t_{TAS} (total access time).
- WE:** Write Enable. Parameters include t_{WCS} (write cycle setup time) and t_{WCH} (write cycle hold time).
- L I/O:** Data In/Out. Parameters include t_{DS} (data setup time) and t_{DH} (data hold time).

In the fast page mode, read, write and read modify write cycles are available for each of the consecutive CAS cycles within the same RAS cycle.

[illegible]

787

[illegible]

Remark In this cycle, the input data to Lower I/O is ineffective.
In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{\text{CAS}}$ cycles within the same $\overline{\text{RAS}}$ cycle.

The timing diagram illustrates the electrical characteristics of the 28C01B EPROM. It shows the relationship between several control and data signals over time. The signals and their associated timing parameters are as follows:

- RAS** (V_{IH} , V_{IL}): Row Address Strobe. Timing parameters include t_{RASP} (pulse width), t_{RHP} (hold time), t_{RP} (return time), and t_{CRP} (setup time).
- UCAS** (V_{IH} , V_{IL}): Column Address Strobe. Timing parameters include t_{MRH} (high time).
- LCAS** (V_{IH} , V_{IL}): Local Column Address Strobe. Timing parameters include t_{CSP} , t_{CSD} , t_{CAS} , t_{CP} , t_{CPC} , t_{CRH} , and t_{CPN} .
- Address** (V_{IH} , V_{IL}): Shows Row and Column address periods. Timing parameters include t_{ASR} , t_{RAH} , t_{ASC} , t_{CAH} , t_{ASC} , t_{CAH} , t_{ASC} , t_{CAH} , t_{ASC} , t_{CAH} , t_{ASC} , t_{CAH} , t_{RCS} , t_{WP} , t_{RCS} , t_{WP} , t_{RCS} , t_{WP} , t_{OEH} , t_{OED} , t_{DS} , t_{DH} , t_{OED} , t_{DS} , t_{DH} , t_{OED} , t_{DS} , t_{DH} .
- WE** (V_{IH} , V_{IL}): Write Enable. Timing parameters include t_{RCS} , t_{WP} , t_{RCS} , t_{WP} , t_{RCS} , t_{WP} , t_{OEH} , t_{OED} , t_{DS} , t_{DH} , t_{OED} , t_{DS} , t_{DH} .
- OE** (V_{IH} , V_{IL}): Output Enable. Timing parameters include t_{OEH} , t_{OED} , t_{DS} , t_{DH} , t_{OED} , t_{DS} , t_{DH} .
- L I/O** (V_{IH} , V_{IL}): Data bus for the Latch. Timing parameters include t_{OED} , t_{DS} , t_{DH} , t_{OED} , t_{DS} , t_{DH} .
- U I/O** (V_{IH} , V_{IL}): Data bus for the User. Timing parameters include t_{OED} , t_{DS} , t_{DH} , t_{OED} , t_{DS} , t_{DH} .

Remark In this cycle, the input data to Upper I/O is ineffective.
In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{\text{CAS}}$ cycles within the same $\overline{\text{RAS}}$ cycle.

[illegible]

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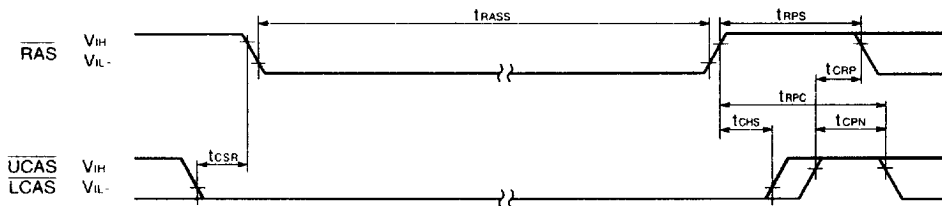
[illegible]

791

792

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CAS Before RAS Self Refresh Cycle (Only for the μ PD42S4260L)



Remark Address, $\overline{WE}$, $\overline{OE}$: Don't care L I/O, U I/O : Hi - Z

Cautions on Use of $\overline{CAS}$ Before $\overline{RAS}$ Self Refresh

$\overline{CAS}$ before $\overline{RAS}$ self refresh can be used independently when used in combination with distributed $\overline{CAS}$ before $\overline{RAS}$ long refresh; However, when used in combination with burst $\overline{CAS}$ before $\overline{RAS}$ long refresh or with burst long $\overline{RAS}$ only refresh, the following cautions must be observed.

(1) Normal Combined Use of $\overline{CAS}$ Before $\overline{RAS}$ Self Refresh and Burst $\overline{CAS}$ Before $\overline{RAS}$ Long Refresh

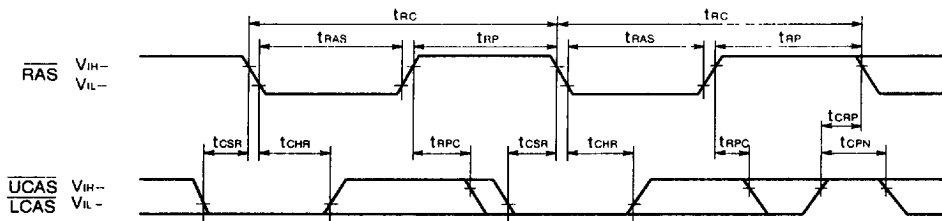
When $\overline{CAS}$ before $\overline{RAS}$ self refresh and burst $\overline{CAS}$ before $\overline{RAS}$ long refresh are used in combination, please perform $\overline{CAS}$ before $\overline{RAS}$ refresh 512 times within a 8 ms interval just before and after setting $\overline{CAS}$ before $\overline{RAS}$ self refresh.

(2) Normal Combined Use of $\overline{CAS}$ Before $\overline{RAS}$ Self Refresh and Burst Long $\overline{RAS}$ Only Refresh

When $\overline{CAS}$ before $\overline{RAS}$ self refresh and burst $\overline{RAS}$ only refresh are used in combination, please perform $\overline{RAS}$ only refresh 512 times within an interval of 8 ms or less just before and after setting $\overline{CAS}$ before $\overline{RAS}$ self refresh.

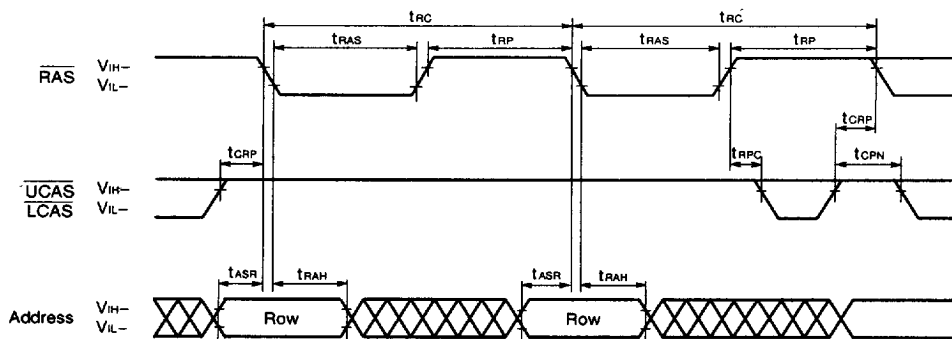
For details, please refer to **How to use DRAM** User's Manual.

CAS Before RAS Refresh Cycle



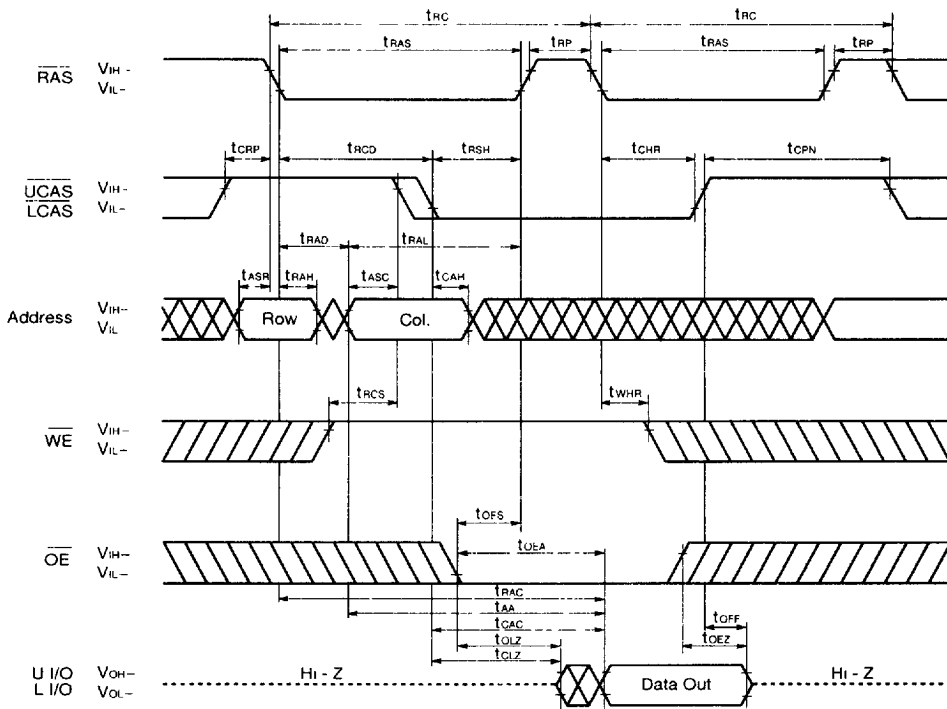
Remark Address, $\overline{WE}$, $\overline{OE}$: Don't care L I/O, U I/O : Hi - Z

RAS Only Refresh Cycle

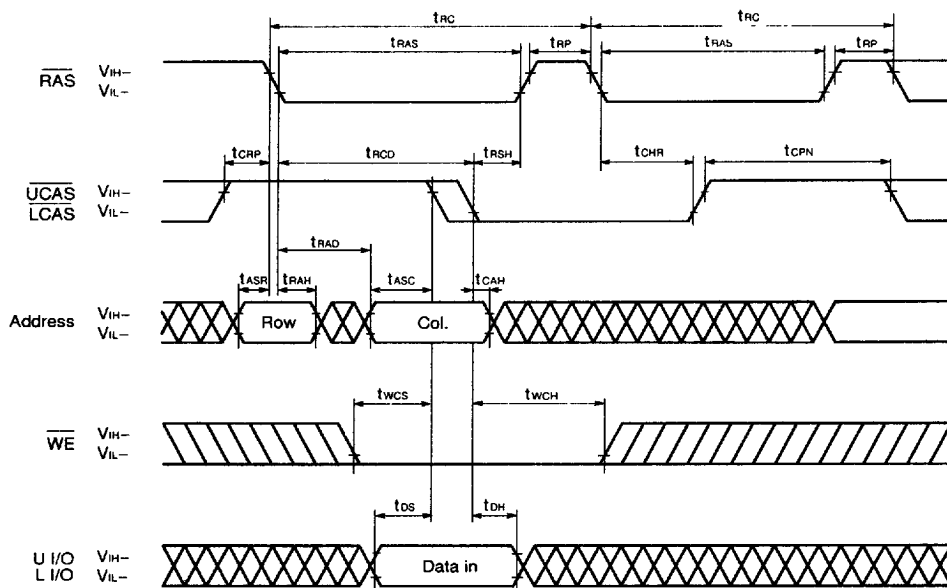


Remark $\overline{WE}$, $\overline{OE}$: Don't care L I/O, U I/O : Hi - Z

Hidden Refresh Cycle (Read)



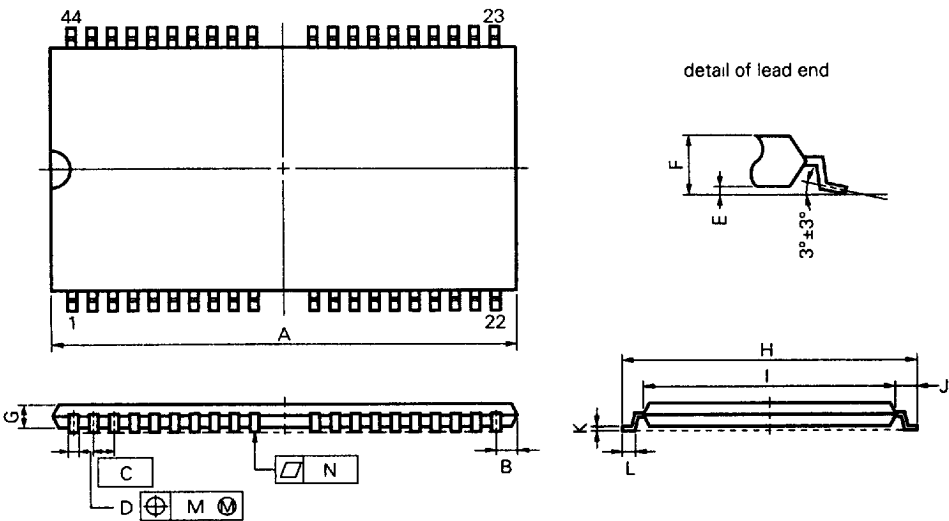
Hidden Refresh Cycle (Write)



Remark $\overline{\text{OE}}$: Don't care

Package Drawings

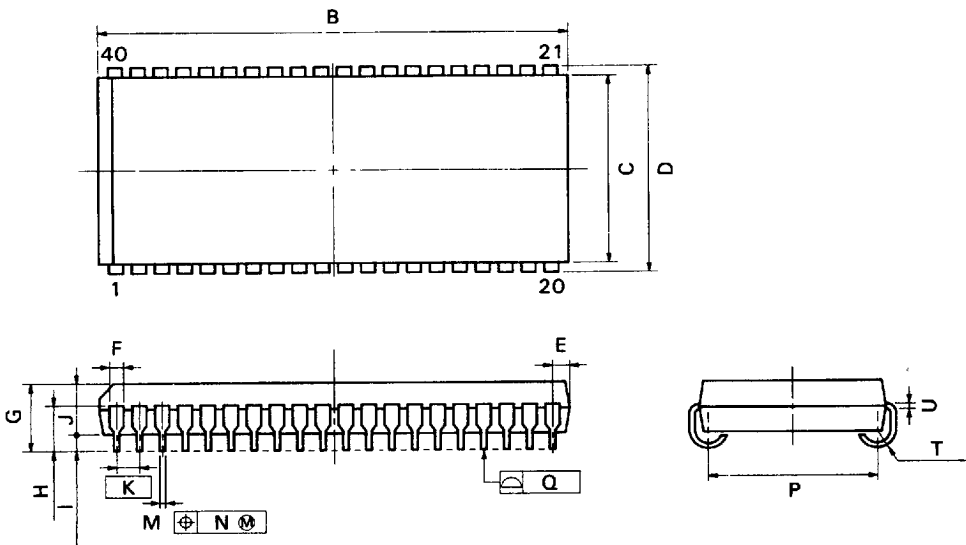
44 PIN PLASTIC TSOP(II) (400 mil)



NOTE
Each lead centerline is located within 0.13 mm (0.005 inch) of its true position (T.P.) at maximum material condition

S44G5-80-7JF-1		
ITEM	MILLIMETERS	INCHES
A	18.81 MAX.	0.741 MAX.
B	1.0 MAX.	0.040 MAX.
C	0.8 (T.P.)	0.031 (T.P.)
D	0.30±0.10	0.012 ^{+0.004} _{-0.005}
E	0.05±0.05	0.002±0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	11.76±0.2	0.463±0.008
I	10.16±0.1	0.400±0.004
J	0.8±0.2	0.031 ^{+0.009} _{-0.008}
K	0.125 ^{+0.10} _{-0.05}	0.005 ^{+0.004} _{-0.002}
L	0.5±0.1	0.020 ^{+0.004} _{-0.005}
M	0.13	0.005
N	0.10	0.004

40PIN PLASTIC SOJ (400 mil)



NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

P40LE-400A-1

ITEM	MILLIMETERS	INCHES
B	26.29 ^{+0.2} _{-0.35}	1.035 ^{+0.008} _{-0.014}
C	10.16	0.400
D	11.18±0.2	0.440±0.008
E	1.08±0.15	0.043 ^{+0.008} _{-0.007}
F	0.7	0.028
G	3.5±0.2	0.138±0.008
H	2.4±0.2	0.094 ^{+0.008} _{-0.008}
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27(T.P.)	0.050(T.P.)
M	0.40±0.10	0.016 ^{+0.004} _{-0.004}
N	0.12	0.005
P	9.4±0.20	0.370±0.008
Q	0.15	0.006
T	R 0.85	R 0.033
U	0.20 ^{+0.10} _{-0.08}	0.008 ^{+0.004} _{-0.004}

Recommended Soldering Conditions

The following conditions (see tables below and next page) must be met when soldering μ PD42S4260L, 424260L.

For more details, refer to our document "SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL" (IEI-1207).

Please consult with our sales offices in case other soldering process is used, or in case the soldering is done under different conditions.

Types of Surface Mount Device

μ PD42S4260LG5, 424260LG5 : 44-pin plastic TSOP (II) (400 mil)

Soldering process	Soldering conditions	Symbol
Infrared ray reflow	Peak temperature of package surface : 235 °C or below, Reflow time: 30 seconds or below (210 °C or higher), Number of reflow processes: MAX. 2 Exposure limit ^{Note} : 7 days (10 hours pre-baking is required at 125 °C afterwards) [Remark] (1) Please start the second reflow process after the temperature, raised by the first reflow process, returns to normal. (2) Please avoid removing the residual flux with water after the first reflow process .	IR35-107-2
VPS	Peak temperature of package : 215 °C or below, Reflow time : 40 seconds or below (200 °C or higher), Number of reflow processes: MAX. 2 Exposure limit ^{Note} : 7 days (10 hours pre-baking is required at 125 °C afterwards) [Remark] (1) Please start the second reflow process after the temperature, raised by the first reflow process, returns to normal. (2) Please avoid removing the residual flux with water after the first reflow process .	VP15-107-2
Partial heating method	Terminal temperature: 300 °C or below, Time : 3 seconds or below (Per one side of the device).	—

Note Exposure limit before soldering after dry-pack package is opened.

Storage conditions: 25 °C and relative humidity at 65 % or less.

Caution Do not apply more than one soldering method at any one time, except for "Partial heating method".

μPD42S4260LLE, 424260LLE : 44-pin plastic SOJ (400 ml)

Soldering process	Soldering conditions	Symbol
Infrared ray reflow	Peak temperature of package surface : 235 °C or below, Reflow time: 30 seconds or below (210 °C or higher), Number of reflow processes: MAX. 2 Exposure limit^{Note}: 7 days (20 hours pre-baking is required at 125 °C afterwards) [Remark] (1) Please start the second reflow process after the temperature, raised by the first reflow process, returns to normal. (2) Please avoid removing the residual flux with water after the first reflow process.	IR35-207-2
VPS	Peak temperature of package : 215 °C or below, Reflow time : 40 seconds or below (200 °C or higher), Number of reflow processes: MAX. 2 Exposure limit^{Note}: 7 days (20 hours pre-baking is required at 125 °C afterwards) [Remark] (1) Please start the second reflow process after the temperature, raised by the first reflow process, returns to normal. (2) Please avoid removing the residual flux with water after the first reflow process.	VP15-207-2
Partial heating method	Terminal temperature: 300 °C or below, Time : 3 seconds or below (Per one side of the device).	—

Note Exposure limit before soldering after dry-pack package is opened.
Storage conditions: 25 °C and relative humidity at 65 % or less.

Caution Do not apply more than one soldering method at any one time, except for "Partial heating method".